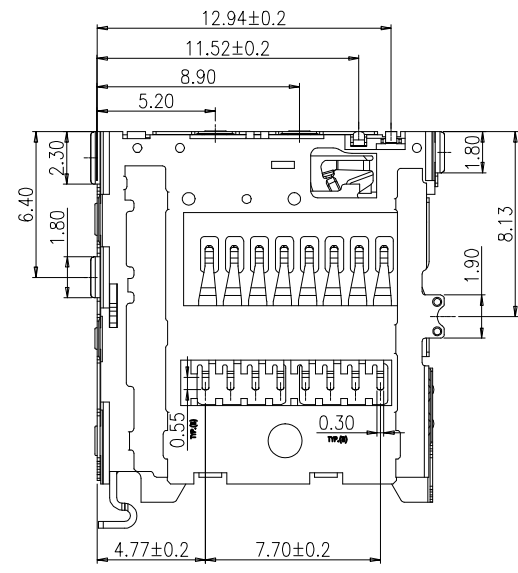
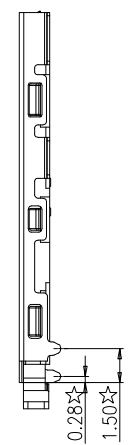
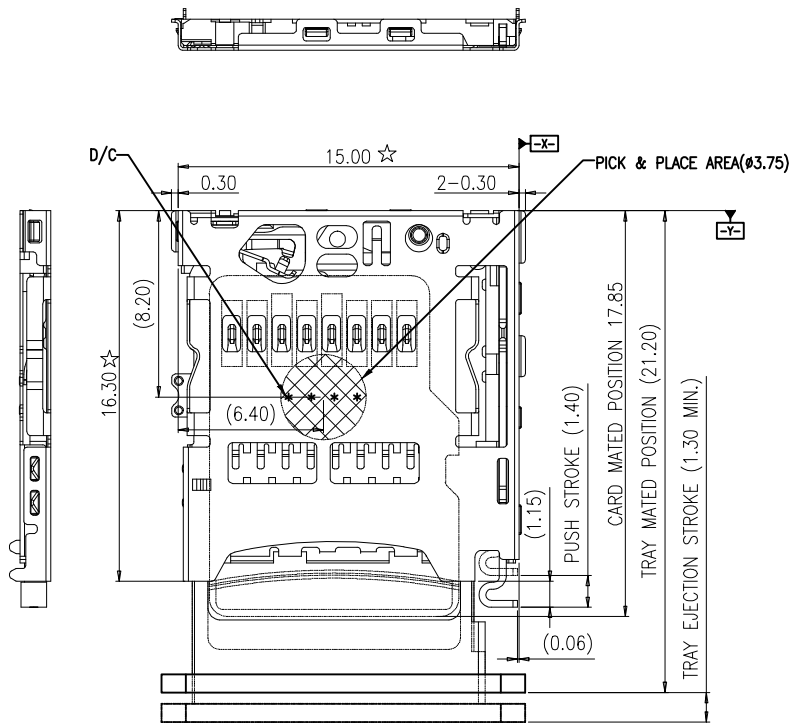
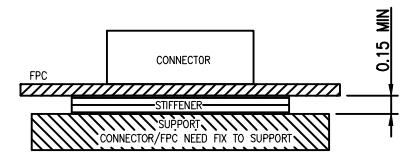
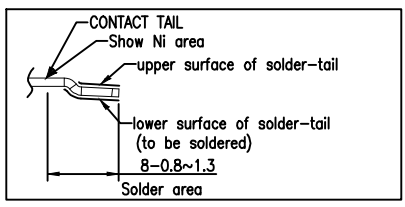
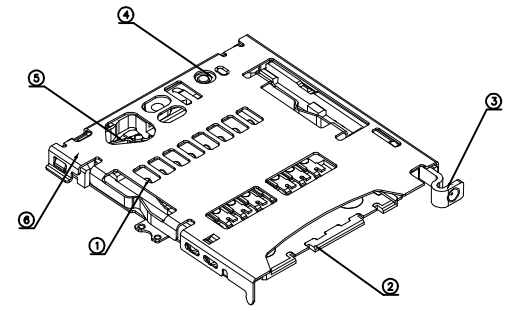
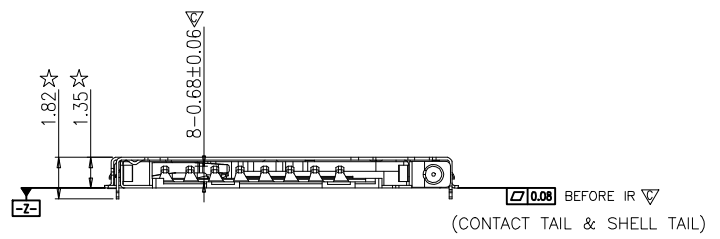


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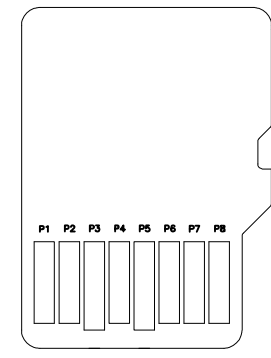
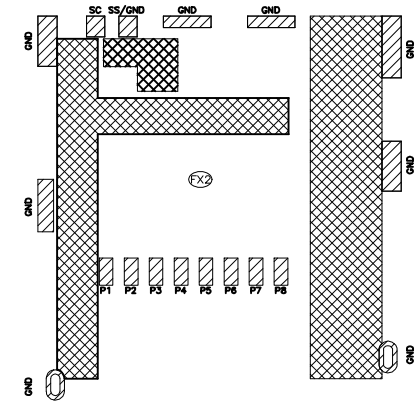
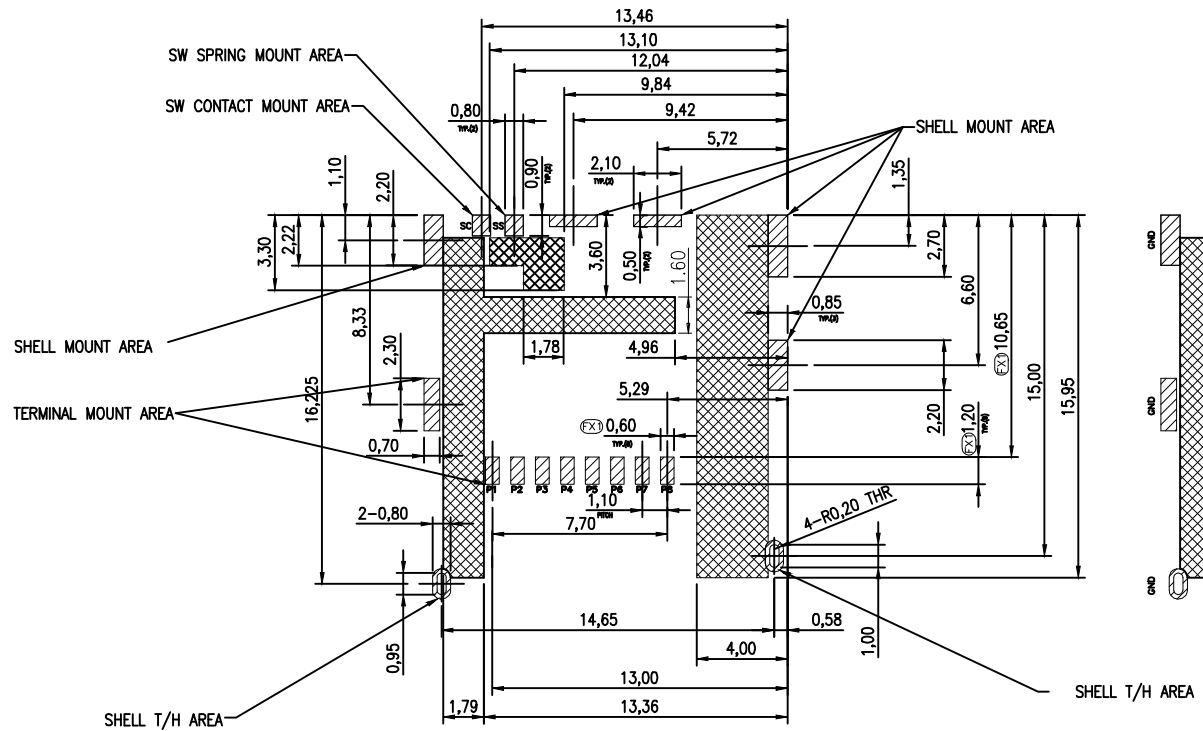
- NOTES:
- MATERIAL:
    - SEE THE ATTACHED TABLE
    - PLATING SPEC. AS BELOW:
  - SPECIFICATION:
    - ELECTRICAL CHARACTERISTICS:
      - CURRENT RATING: 0.5A MAX./PIN
      - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE
      - CONTACT RESISTANCE: 50 mOhm MAX.
      - INSULATION RESISTANCE: 1000 Megohms MIN.
    - MECHANICAL CHARACTERISTICS:
      - DURABILITY: 2000 CYCLES
      - TRAY MATING FORCE: 15N MAX.; TRAY UNMATING FORCE: 3N MIN.
  - RECOMMENDED PROCESS CONDITION: IR-REFLOW, PEAK TEMPERATURE AND TIME: 250°C, 5~10S. BEFORE IR-REFLOW THE CO-PLANARITY 0.08MM MAX; AFTER 2 TIMES IR-REFLOW THE CO-PLANARITY 0.10MM MAX
  - DIMENSIONS MARKED ☆ SHOULD BE CHECKED BY Q.C. AND PROCESS ENGINEERS, AND DIMENSIONS MARKED ▽ SHOULD CHECK THE CPK DATE
  - RECOMMEND METAL MASK: THICKNESS IN CASE OF STENCIL IS 0.12MM. OPEN RATIO IS 100%
  - RECOMMENDED PCB THICKNESS: 0.6~1.0 MM.



ITEM	PART NAME	Q'TY	MATERIAL	FINISHING	REMARK
6	SWITCH	1	COPPER ALLOY	Contact Area: 15u" Au & Solder Area: 1u" Au	
5	LEVER	1	STAINLESS STEEL	CLEANING	
4	CAM	1	STAINLESS STEEL	CLEANING	
3	I/M HSG	1	THERMOPLASTIC	BLACK COLOR, UL94-V0	
2	CONTACT	1	COPPER ALLOY	Contact Area: 15u" Au & Solder Area: 1u" Au	
1	SHELL	1	STAINLESS STEEL	Solder Area: 1u" Au	

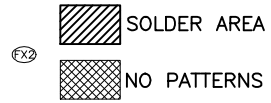
GENERAL TOLERANCE		DWG NO.	JYSA1229-001	APPD:	WIND	Scale	1:1
X.±0.45	x.±5'	Title	1.35H PIN PUSH T-Flash CARD CONN (With Tray)	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM135-064	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'			Shenzhen <b>JYSCONN Electronics Co., LTD.</b>			
SHEET	1/3						

REV.	ECN.NO.	MODIFY.CONTENT	DATE
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MSD CARD ELECTRICAL

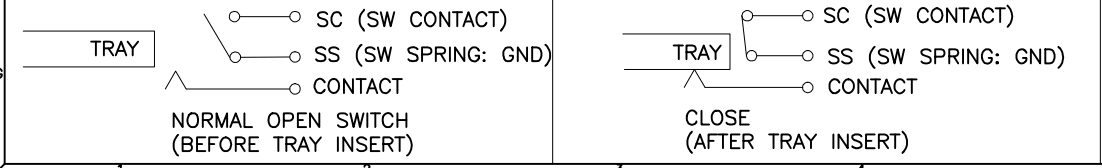
RECOMMENDED P.W.BOARD PATTERN LAYOUT  
SUGGEST PCB THICKNESS 0.7MM MIN  
TOLERANCE: +/-0.05



CONNECTOR PIN ASSIGNMENT:

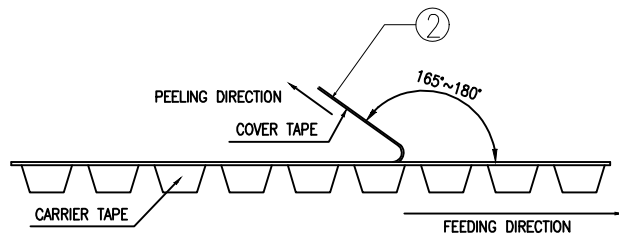
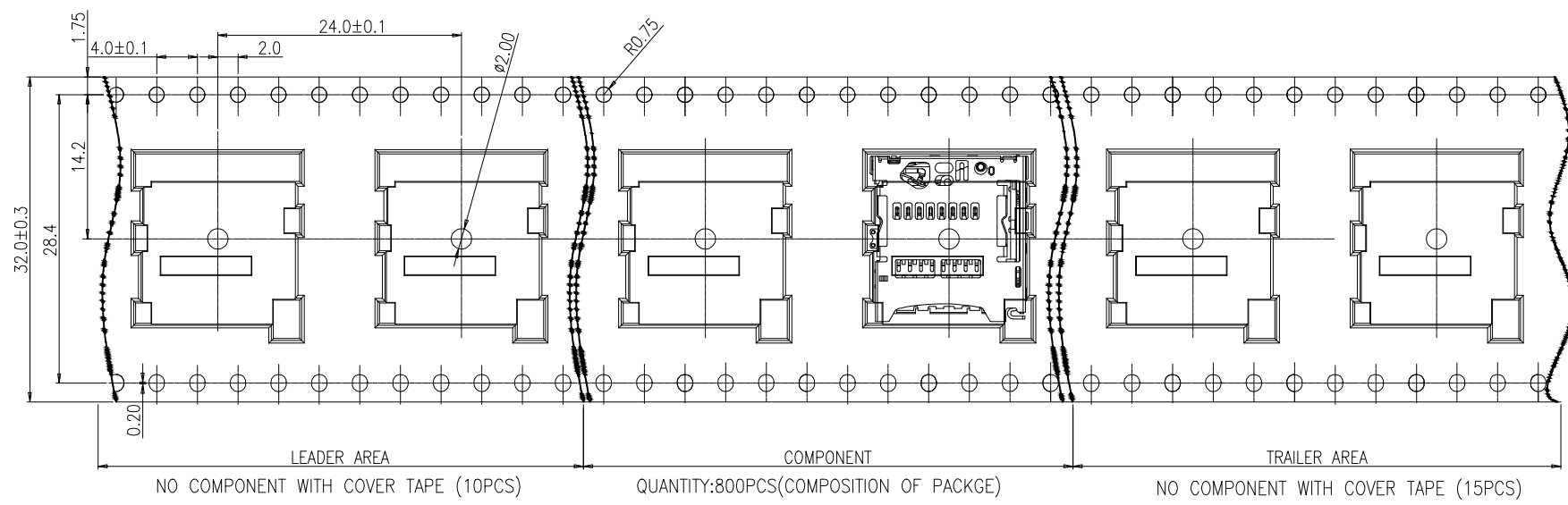
ITEM	FUNCTION
MICRO SD CARD	
P1	DATA1 OF MSD
P2	DATA0 OF MSD
P3	VSS OF MSD
P4	CLK OF MSD
P5	VDD OF MSD
P6	CMD OF MSD
P7	CD/DAT3 OF MSD
P8	DATA2 OF MSD
SC	SW CONTACT
SS	SW SPRING

CIRCUIT DIAGRAM FOR DETECT SWITCHES

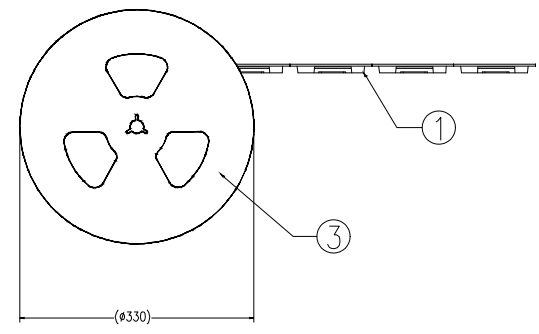


GENERAL TOLERANCE		DWG NO.	JYSA1229-001	APPD:	WIND	Scale	1:1
X.±0.45	x.±5'	Title	1.35H PIN PUSH T-Flash CARD CONN (With Tray)	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM135-064	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'	Shenzhen		<b>JYCONN Electronics Co., LTD.</b>			
SHEET 2/3							

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2019/05/29



- NOTES:
1. POCKET HOLE PITCH CLUMATIVE TOLERANCE  $\pm 0.40\text{mm}$
  2. PACKAGEING CAPACITY:  
800pcs/REEL; 8REEL/CARTON ; TOTAL: 6400PCS/CARTON
  3. PACKAGING USE ATTENTION:  
NOT TWISTED OVER 90° WITHIN 1000mm.



GENERAL TOLERANCE		DWG NO.	JYSA1229-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	1.35H PIN PUSH T-Flash CARD CONN (With Tray)	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM135-064	Date	2019/05/29		
.XXX±0.15	.xxx'±0.5'			Shenzhen <b>JYSCONN Electronics Co., LTD.</b>			
SHEET	3/3						